

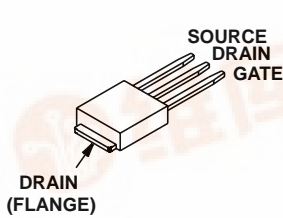
**18A, 150V, 0.110 Ohm, N-Channel,
UltraFET Power MOSFET**



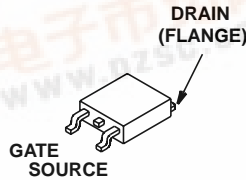
Packaging

JEDEC TO-251AA

JEDEC TO-252AA



HUF75829D3

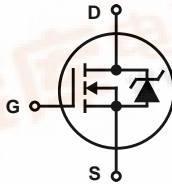


HUF75829D3S

Features

- Ultra Low On-Resistance
 - $r_{DS(ON)} = 0.110\Omega, V_{GS} = 10V$
- Simulation Models
 - Temperature Compensated PSPICE® and SABER® Electrical Models
 - Spice and SABER® Thermal Impedance Models
 - www.intersil.com
- Peak Current vs Pulse Width Curve
- UIS Rating Curve

Symbol



Ordering Information

PART NUMBER	PACKAGE	BRAND
HUF75829D3	TO-251AA	75829D
HUF75829D3S	TO-252AA	75829D

NOTE: When ordering, use the entire part number. Add the suffix T to obtain the variant in tape and reel, e.g., HUF75829D3ST.

Absolute Maximum Ratings $T_C = 25^\circ C$, Unless Otherwise Specified

	HUF75829D3, HUF75829D3S	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	150 V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	V_{DGR}	150 V
Gate to Source Voltage	V_{GS}	± 20 V
Drain Current		
Continuous ($T_C = 25^\circ C, V_{GS} = 10V$) (Figure 2)	I_D	18 A
Continuous ($T_C = 100^\circ C, V_{GS} = 10V$) (Figure 2)	I_D	13 A
Pulsed Drain Current	I_{DM}	Figure 4
Pulsed Avalanche Rating	UIS	Figures 6, 14, 15
Power Dissipation	P_D	110 W
Derate Above $25^\circ C$		0.73 $W/^\circ C$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175 $^\circ C$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300 $^\circ C$
Package Body for 10s, See Techbrief TB334	T_{pkg}	260 $^\circ C$

NOTES:

1. $T_J = 25^\circ C$ to $150^\circ C$.

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.



HUF75829D3, HUF75829D3S

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
OFF STATE SPECIFICATIONS							
Drain to Source Breakdown Voltage	BV_{DSS}	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$ (Figure 11)	150	-	-	V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 140\text{V}$, $V_{GS} = 0\text{V}$	-	-	1	μA	
		$V_{DS} = 135\text{V}$, $V_{GS} = 0\text{V}$, $T_C = 150^\circ\text{C}$	-	-	250	μA	
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}$	-	-	± 100	nA	
ON STATE SPECIFICATIONS							
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$ (Figure 10)	2	-	4	V	
Drain to Source On Resistance	$r_{DS(ON)}$	$I_D = 18\text{A}$, $V_{GS} = 10\text{V}$ (Figure 9)	-	0.0925	0.110	Ω	
THERMAL SPECIFICATIONS							
Thermal Resistance Junction to Case	$R_{\theta JC}$	TO-251 and TO-252	-	-	1.36	$^\circ\text{C/W}$	
Thermal Resistance Junction to Ambient	$R_{\theta JA}$		-	-	100	$^\circ\text{C/W}$	
SWITCHING SPECIFICATIONS ($V_{GS} = 10\text{V}$)							
Turn-On Time	t_{ON}	$V_{DD} = 75\text{V}$, $I_D = 18\text{A}$ $V_{GS} = 10\text{V}$, $R_{GS} = 10\Omega$ (Figures 18, 19)	-	-	58	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	8.5	-	ns	
Rise Time	t_r		-	30	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	53	-	ns	
Fall Time	t_f		-	30	-	ns	
Turn-Off Time	t_{OFF}		-	-	125	ns	
GATE CHARGE SPECIFICATIONS							
Total Gate Charge	$Q_{g(TOT)}$	$V_{GS} = 0\text{V to } 20\text{V}$	$V_{DD} = 75\text{V}$, $I_D = 18\text{A}$, $I_{g(REF)} = 1.0\text{mA}$ (Figures 13, 16, 17)	-	58	70	nC
Gate Charge at 10V	$Q_{g(10)}$	$V_{GS} = 0\text{V to } 10\text{V}$		-	31	37	nC
Threshold Gate Charge	$Q_{g(TH)}$	$V_{GS} = 0\text{V to } 2\text{V}$		-	2.1	2.5	nC
Gate to Source Gate Charge	Q_{gs}			-	4.6	-	nC
Gate to Drain "Miller" Charge	Q_{gd}			-	11	-	nC
CAPACITANCE SPECIFICATIONS							
Input Capacitance	C_{ISS}	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$ (Figure 12)	-	1080	-	pF	
Output Capacitance	C_{OSS}		-	260	-	pF	
Reverse Transfer Capacitance	C_{RSS}		-	90	-	pF	

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	$I_{SD} = 18\text{A}$	-	-	1.25	V
		$I_{SD} = 9\text{A}$	-	-	1.00	V
Reverse Recovery Time	t_{rr}	$I_{SD} = 18\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	155	ns
Reverse Recovered Charge	Q_{RR}	$I_{SD} = 18\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	800	nC

HUF75829D3, HUF75829D3S

Typical Performance Curves

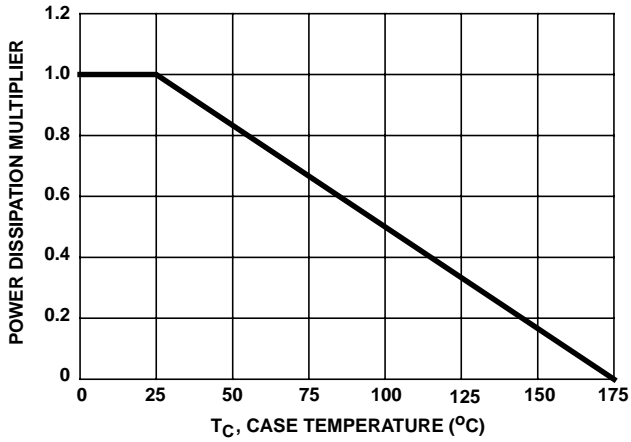


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

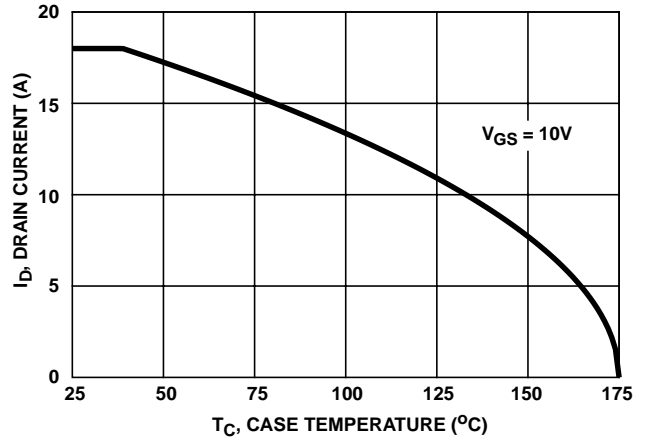


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

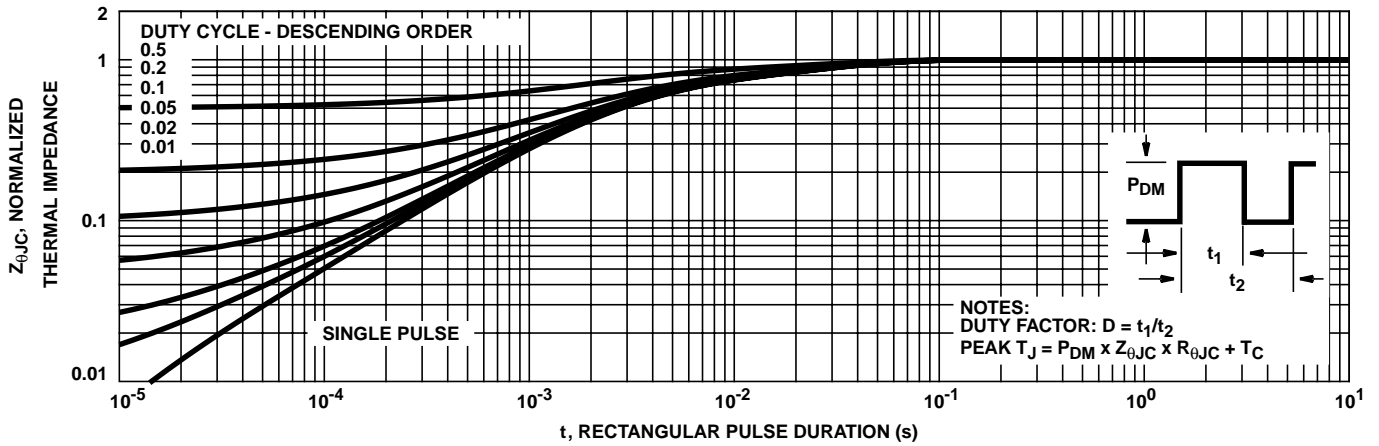


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

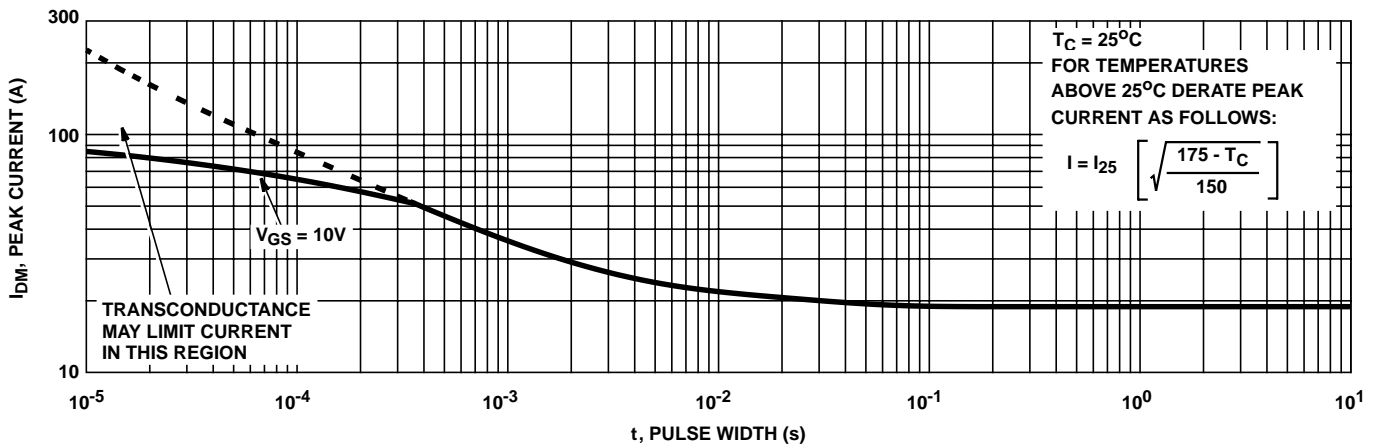


FIGURE 4. PEAK CURRENT CAPABILITY

HUF75829D3, HUF75829D3S

Typical Performance Curves (Continued)

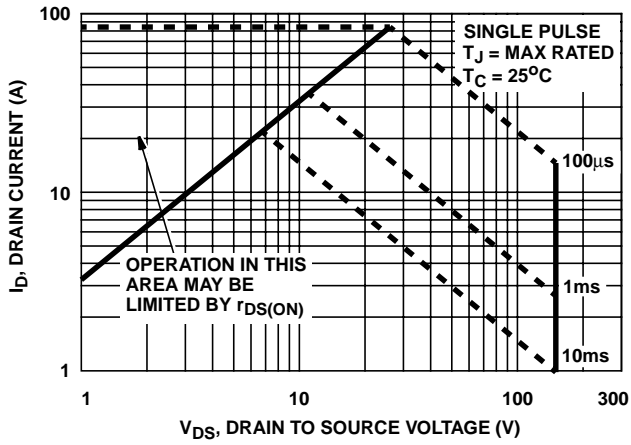
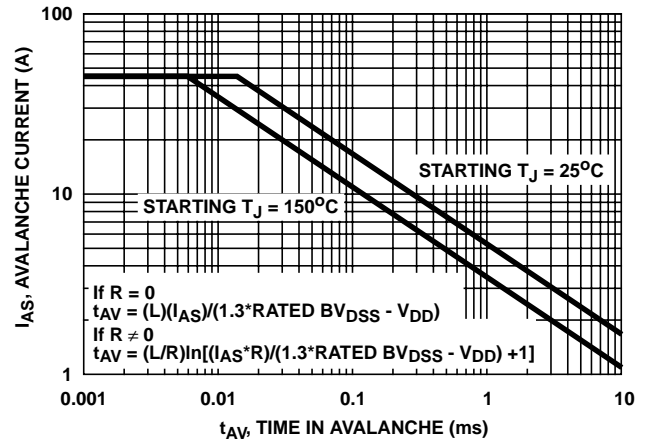


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA



NOTE: Refer to Intersil Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

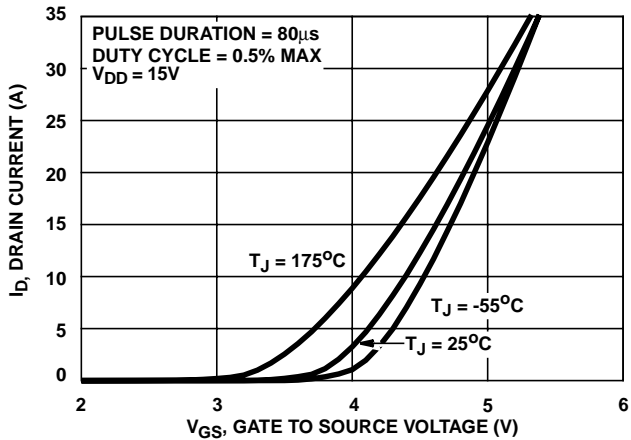


FIGURE 7. TRANSFER CHARACTERISTICS

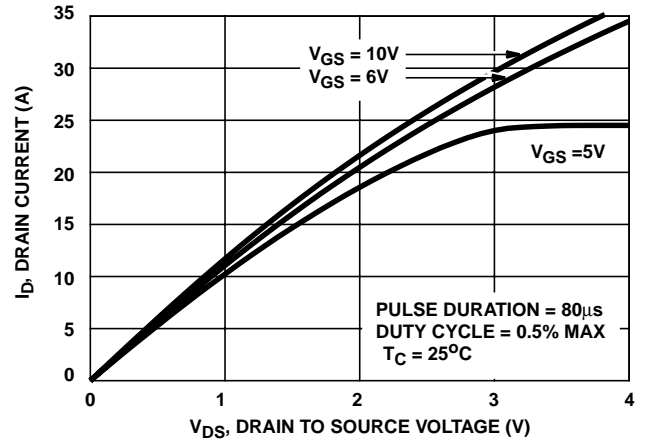


FIGURE 8. SATURATION CHARACTERISTICS

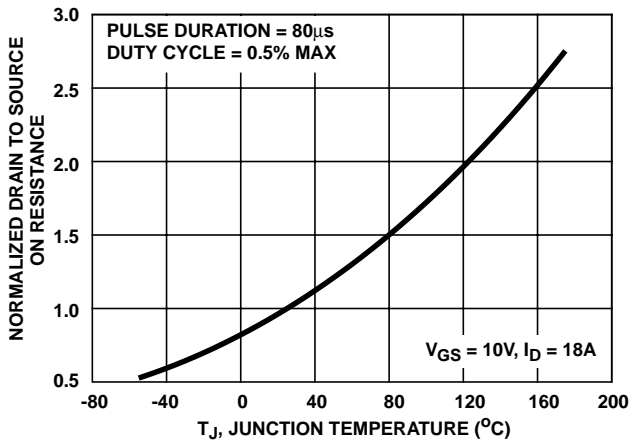


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

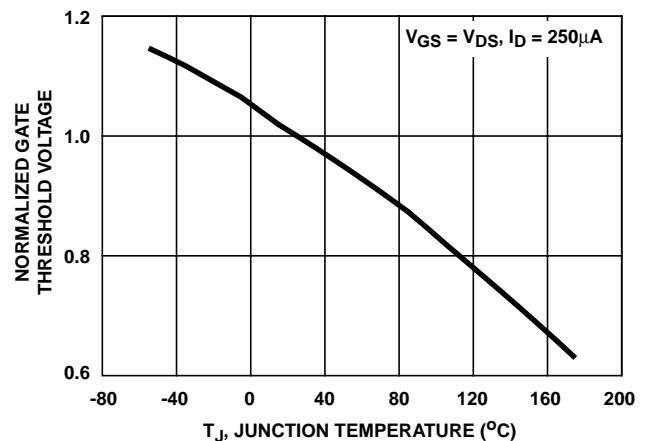


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

Typical Performance Curves (Continued)

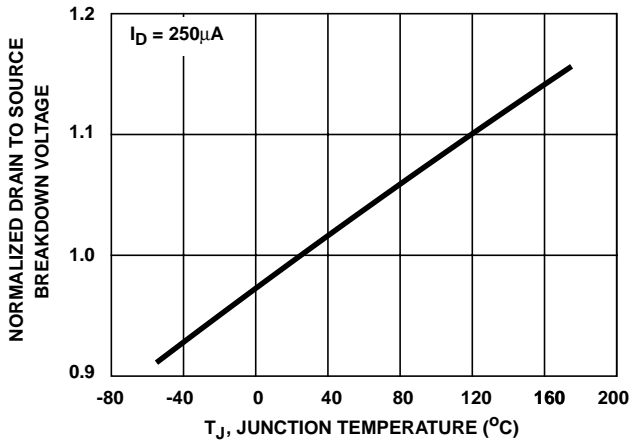


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

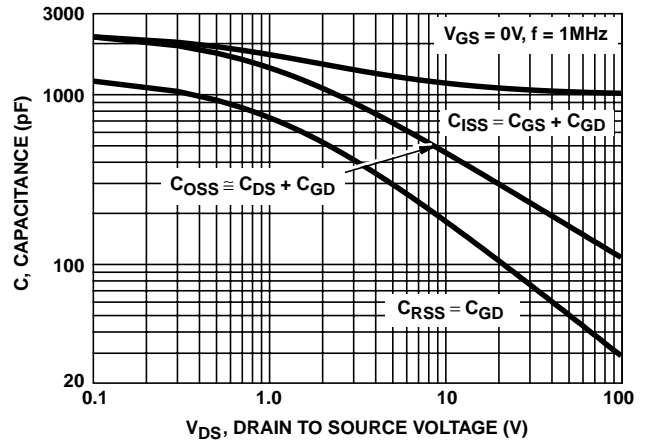
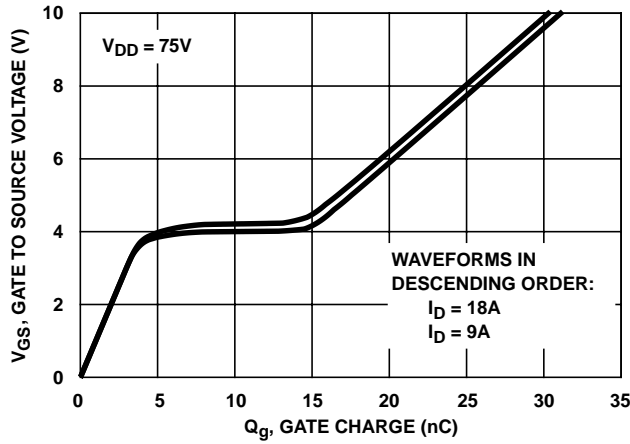


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Intersil Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

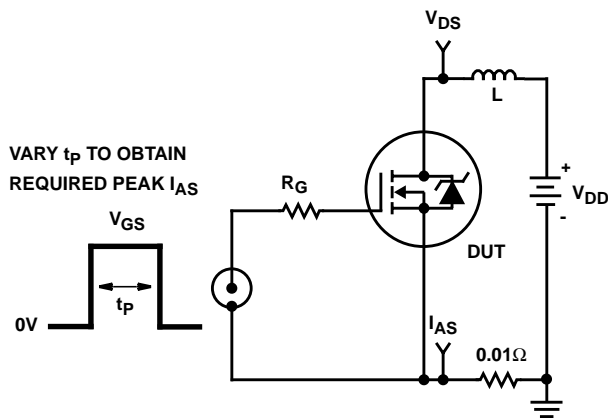


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

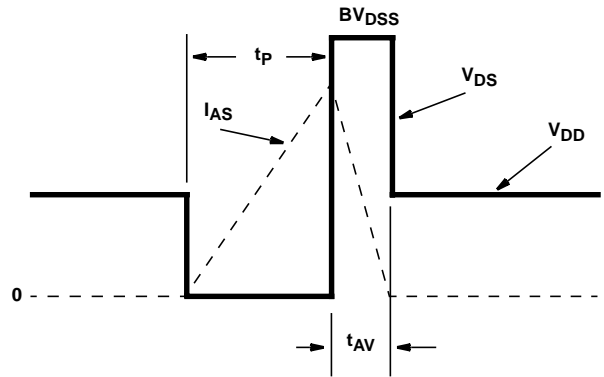


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

Test Circuits and Waveforms (Continued)

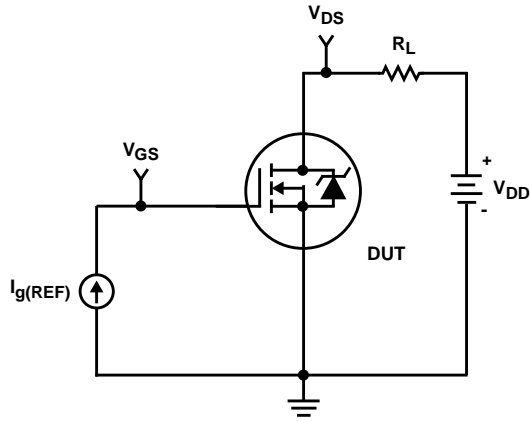


FIGURE 16. GATE CHARGE TEST CIRCUIT

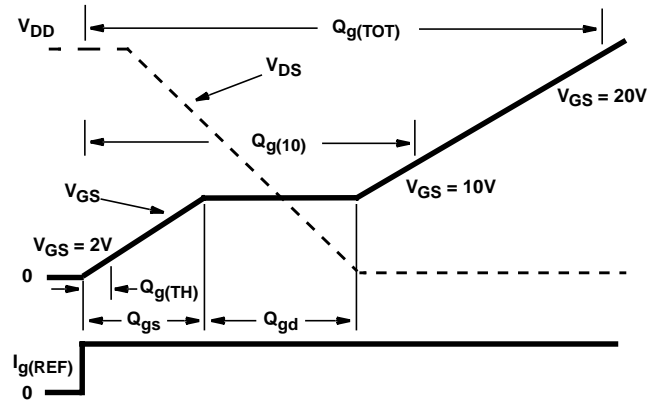


FIGURE 17. GATE CHARGE WAVEFORMS

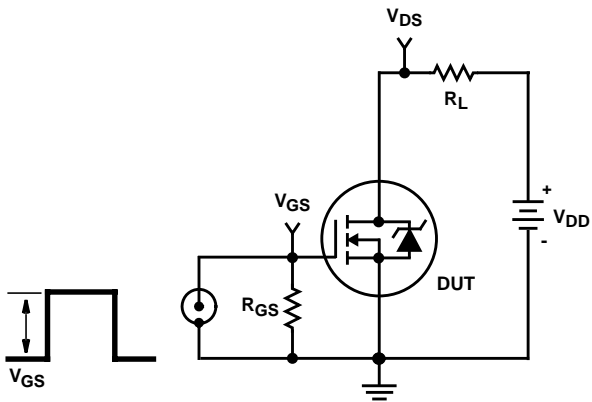


FIGURE 18. SWITCHING TIME TEST CIRCUIT

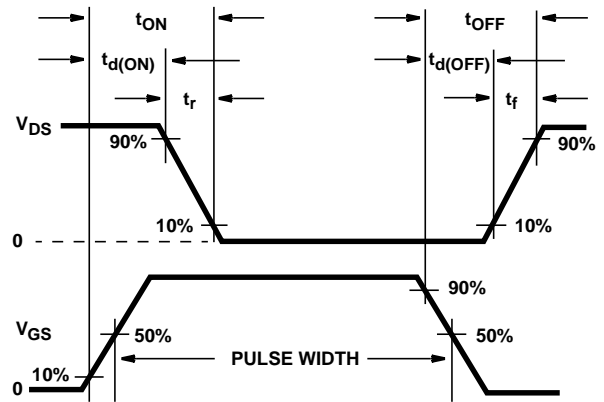


FIGURE 19. SWITCHING TIME WAVEFORM

HUF75829D3, HUF75829D3S

SABER Electrical Model

REV 4 January 2000

template huf75829 n2,n1,n3
electrical n2,n1,n3

```
{
var i iscl
dp..model dbodymod = (is = 8.80e-13, rs=1.05e-2, xti=5, trs1=2.20e-3, trs2=3.70e-6, cjo = 1.04e-9, tt = 9.90e-8, m = 0.55)
dp..model dbreakmod = (rs=1.05, trs1=1.80e-3, trs2=3.00e-6)
dp..model dplcapmod = (cjo = 1.30e-9, is = 1e-30, m = 0.82)
m..model mmedmod = (type=_n, vto = 3.22, kp = 5, is = 1e-30, tox = 1)
m..model mstrongmod = (type=_n, vto = 3.67, kp = 53, is = 1e-30, tox = 1)
m..model mweakmod = (type=_n, vto = 2.78, kp = 0.10, is = 1e-30, tox = 1)
sw_vcsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -5.8, voff = -2.4)
sw_vcsp..model s1bmod = (ron = 1e-5, roff = 0.1, von = -2.4, voff = -5.8)
sw_vcsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -1.8, voff = 0.5)
sw_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.5, voff = -1.8)

```

```
c.ca n12 n8 = 1.70e-9
c.cb n15 n14 = 1.70e-9
c.cin n6 n8 = 9.90e-10

```

```
dp.dbody n7 n5 = model=dbodymod
dp.dbreak n5 n11 = model=dbreakmod
dp.dplcap n10 n5 = model=dplcapmod

```

i.it n8 n17 = 1

```
l.l drain n2 n5 = 1e-9
l.l gate n1 n9 = 3.11e-9
l.l source n3 n7 = 3.72e-9

```

```
m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u

```

```
res.rbreak n17 n18 = 1, tc1 = 1.10e-3, tc2 = -3.00e-7
res.rdrain n50 n16 = 6.22e-2, tc1 = 9.40e-3, tc2 = 2.70e-5
res.rgate n9 n20 = 2.13
res.rldrain n2 n5 = 10
res.rlgate n1 n9 = 31.1
res.rlsource n3 n7 = 37.2
res.rslc1 n5 n51 = 1e-6, tc1 = 4.10e-3, tc2 = 4.00e-6
res.rslc2 n5 n50 = 1e3
res.rsouce n8 n7 = 1.88e-2, tc1 = 1e-3, tc2 = 1e-6
res.rvtemp n18 n19 = 1, tc1 = -2.60e-3, tc2 = -1.00e-6
res.rvthres n22 n8 = 1, tc1 = -2.40e-3, tc2 = -7.50e-6

```

```
spe.ebreak n11 n7 n17 n18 = 156.5
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1

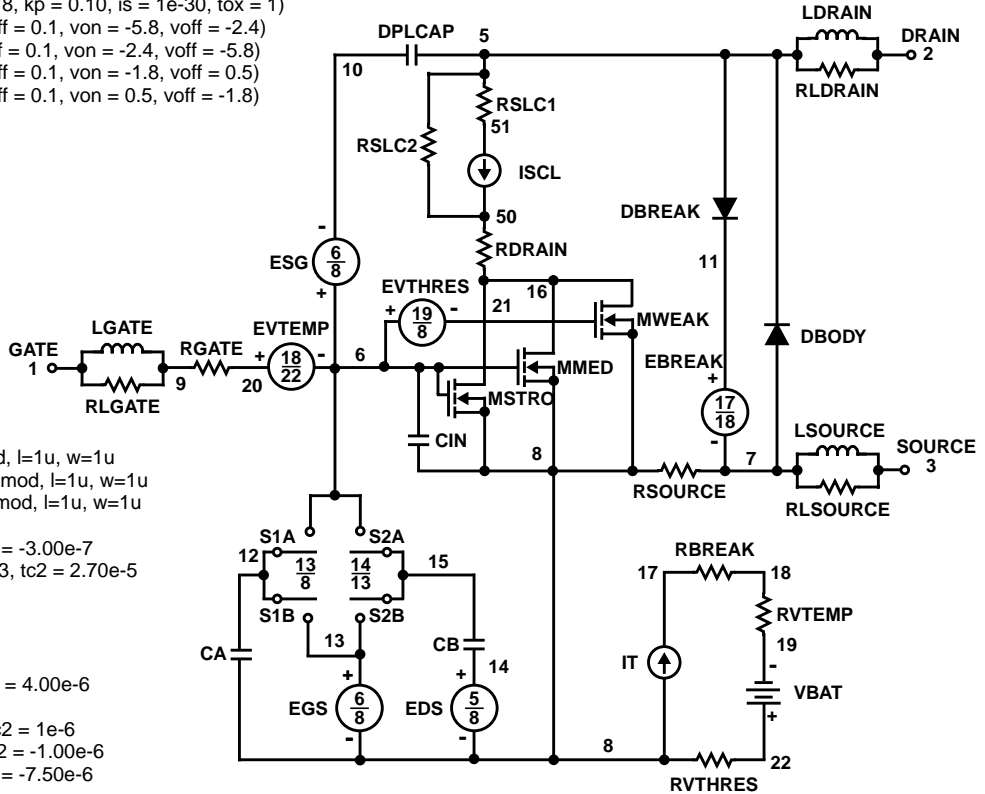
```

```
sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod

```

v.vbat n22 n19 = dc=1

```
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = (((v(n5,n51))/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51))*1e6/36)** 3))
}
}
```



HUF75829D3, HUF75829D3S

SPICE Thermal Model

REV 5 November 1999

HUF75829T

CTHERM1 th 6 2.45e-3
CTHERM2 6 5 8.15e-3
CTHERM3 5 4 7.40e-3
CTHERM4 4 3 7.45e-3
CTHERM5 3 2 1.01e-2
CTHERM6 2 tl 7.49e-2

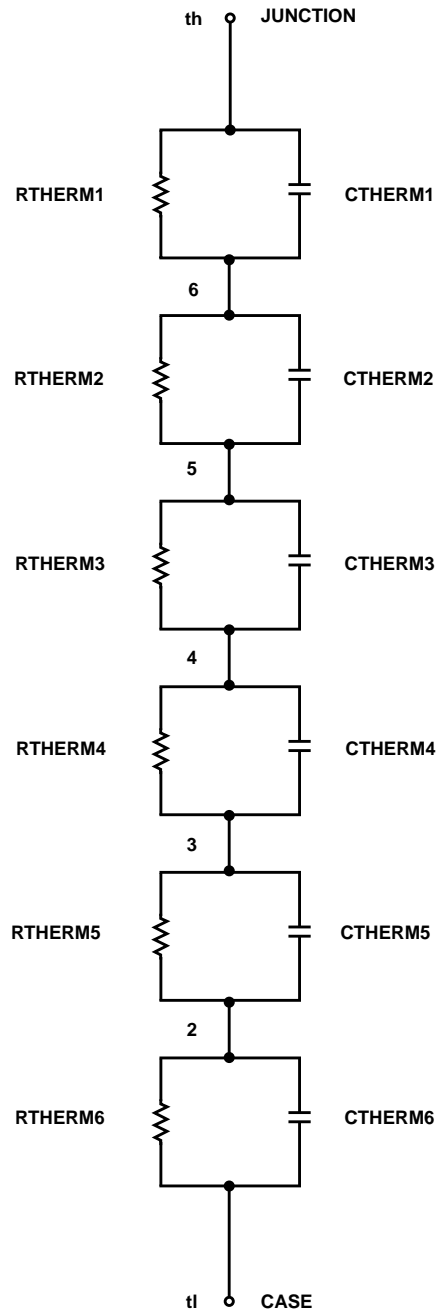
RTHERM1 th 6 9.00e-3
RTHERM2 6 5 1.80e-2
RTHERM3 5 4 9.15e-2
RTHERM4 4 3 2.43e-1
RTHERM5 3 2 3.50e-1
RTHERM6 2 tl 3.62e-1

SABER Thermal Model

SABER thermal model HUF75829T

```
template thermal_model th tl
thermal_c th, tl
{
  ctherm.ctherm1 th 6 = 2.45e-3
  ctherm.ctherm2 6 5 = 8.15e-3
  ctherm.ctherm3 5 4 = 7.40e-3
  ctherm.ctherm4 4 3 = 7.45e-3
  ctherm.ctherm5 3 2 = 1.01e-2
  ctherm.ctherm6 2 tl = 7.49e-2

  rtherm.rtherm1 th 6 = 9.00e-3
  rtherm.rtherm2 6 5 = 1.80e-2
  rtherm.rtherm3 5 4 = 9.15e-2
  rtherm.rtherm4 4 3 = 2.43e-1
  rtherm.rtherm5 3 2 = 3.50e-1
  rtherm.rtherm6 2 tl = 3.62e-1
}
```



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